

General Description

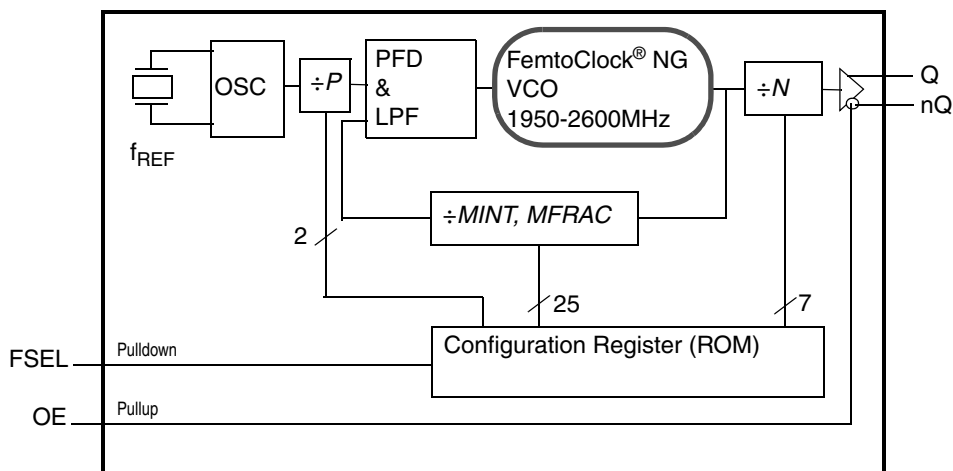
The IDT8N3D085 is a LVPECL Dual Frequency-Programmable Crystal Oscillator with very flexible frequency programming capabilities. The device uses IDT's fourth generation FemtoClock® NG technology for an optimum of high clock frequency and low phase noise performance. The device accepts 2.5V or 3.3V supply and is packaged in a small, lead-free (RoHS 6) 6-lead ceramic 5mm x 7mm x 1.55mm package.

The device can be programmed to any frequency in the range from 15.476MHz to 866.67MHz and from 975MHz to 1,300 MHz and supports a very high degree of frequency precision of 218Hz or better. One of two pre-set output frequencies is selected by the FSEL pin. The extended temperature range supports wireless infrastructure, telecommunication and networking end equipment requirements.

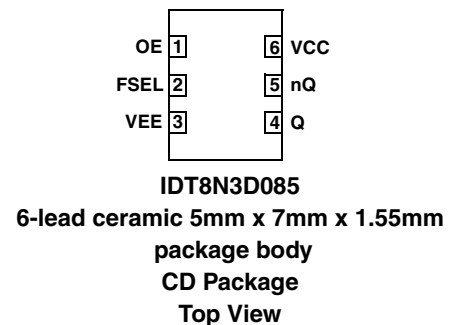
Features

- Fourth generation FemtoClock® NG technology
- Factory-programmable clock output frequency from 15.476MHz to 866.67MHz and from 975MHz to 1,300MHz
- Frequency programming resolution is 218Hz and better
- One 2.5V or 3.3V LVPECL clock output
- Output enable control (positive polarity), LVC MOS/LVTTL compatible
- LVC MOS compatible control inputs
- RMS phase jitter @ 156.25MHz (12kHz - 20MHz): 0.24ps (typical), integer PLL feedback configuration
- RMS phase jitter @ 156.25MHz (1kHz - 40MHz): 0.27ps (typical), integer PLL feedback configurationally
- 2.5V or 3.3V supply
- -40°C to 85°C ambient operating temperature
- Available in a lead-free (RoHS 6) 6-pin ceramic package

Block Diagram



Pin Assignment



Pin Description and Characteristic Tables

Table 1. Pin Descriptions

Number	Name	Type		Description
1	OE	Input	Pullup	Output enable pin. See table 3A for function. LVCMOS/LVTTL interface levels.
2	FSEL	Input	Pulldown	Frequency select pin. See table 3B for function. LVCMOS/LVTTL interface levels.
3	V _{EE}	Power		Negative supply pin.
4, 5	Q, nQ	Output		Differential clock output pair. LVPECL interface levels.
6	V _{CC}	Power		Power supply pin.

NOTE: Pullup and pulldown refer to internal input resistors. See Table 2, *Pin Characteristics*, for typical values.

Table 2. Pin Characteristics

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			5.5		pF
R _{PULLDOWN}	Input Pulldown Resistor			50		kΩ
R _{PULLUP}	Input Pullup Resistor			50		kΩ

Function Tables

Table 3A. OE Configuration

Input	
OE	Output Enable
0	Output Q, nQ is in high-impedance state.
1 (default)	Output Q, nQ is enabled.

NOTE: OE is an asynchronous control.

Table 3B. Frequency Selection

Input	
FSEL	Operation
0 (default)	Frequency 0
1	Frequency 1

NOTE: Frequency 0 and 1 are factory-programmed by IDT. Any frequency combination within the available frequency range (see table 3C) can be ordered. For order information, see *FemtoClock NG Ceramic-Package XO and VCXO Ordering Product Information* document.

Table 3C. Output Frequency Range

15.476MHz to 866.67MHz
975 MHz to 1,300MHz

NOTE: Supported output frequency range. The output frequency can be programmed to any frequency in this range and to a precision of 218 Hz or better.

Principles of Operation

The block diagram consists of the internal 3rd overtone crystal and oscillator which provide the reference clock f_{XTAL} of either 114.285MHz or 100MHz. The PLL includes the FemtoClock NG VCO along with the Pre-divider (P), the feedback divider (M) and the post divider (N). The P, M, and N dividers determine the output frequency based on the f_{XTAL} reference. The configuration of the feedback divider to integer-only values results in an improved output phase noise characteristics at the expense of the range of output frequencies. Internal registers are used to hold up to two different factory pre-set configuration settings. The configuration is selected via the FSEL pin. Changing the FSEL control results in an immediate change of the output frequency to the selected register values. The P, M, and N frequency configurations support an output frequency range from 15.476MHz to 866.67MHz and from 975MHz to 1,300MHz.

The devices use the fractional feedback divider with a delta-sigma modulator for noise shaping and robust frequency synthesis capability. The relatively high reference frequency minimizes phase noise generated by frequency multiplication and allows more efficient shaping of noise by the delta-sigma modulator. The output frequency is determined by the 2-bit pre-divider (P), the feedback divider (M) and the 7-bit post divider (N). The feedback divider (M) consists of both a 7-bit integer portion (MINT) and an 18-bit fractional portion (MFRAC) and provides the means for high-resolution frequency generation. The output frequency f_{OUT} is calculated by:

$$f_{OUT} = f_{XTAL} \cdot \frac{1}{P \cdot N} \cdot \left[MINT + \frac{MFRAC + 0.5}{2^{18}} \right] \quad (1)$$

Table 3D. Frequency Selection

Input	Selects
FSEL	
0 (default)	Frequency 0
1	Frequency 1

Frequency Configuration

An order code is assigned to each frequency configuration and the VCXO pull-range programmed by the factory (default frequencies). For more information on the available default frequencies and order codes, please see the Ordering Information Section in this document. For available order codes, see the FemtoClock NG Ceramic-Package XO and VCXO Ordering Product Information document.

For more information on programming capabilities of the device for custom frequency and pull-range configurations, see the *FemtoClock NG Ceramic 5x7 Module Programming Guide*.

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC*

Characteristics or AC Characteristics is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, V_{CC}	3.63V
Inputs, V_I	-0.5V to $V_{CC} + 0.5V$
Outputs, I_O Continuous Current Surge Current	50mA 100mA
Package Thermal Impedance, θ_{JA}	49.4°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

DC Electrical Characteristics

Table 4A. Power Supply DC Characteristics, $V_{CC} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = -40^\circ C$ to $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Power Supply Voltage		3.135	3.3	3.465	V
I_{EE}	Power Supply Current			123	148	mA

Table 4B. Power Supply DC Characteristics, $V_{CC} = 2.5V \pm 5\%$, $V_{EE} = 0V$, $T_A = -40^\circ C$ to $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Power Supply Voltage		2.375	2.5	2.625	V
I_{EE}	Power Supply Current			119	143	mA

Table 4C. LVCMOS/LVTTL DC Characteristic, $V_{CC} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $V_{EE} = 0V$, $T_A = -40^\circ C$ to $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	$V_{CC} = 3.3V$	2		$V_{CC} + 0.3$	V
		$V_{CC} = 2.5V$	1.7		$V_{CC} + 0.3$	V
V_{IL}	Input Low Voltage	$V_{CC} = 3.3V$	OE	-0.3	0.8	V
			FSEL	-0.3	0.5	V
		$V_{CC} = 2.5V$	OE	-0.3	0.7	V
			FSEL	-0.3	0.5	V
I_{IH}	Input High Current	$V_{CC} = V_{IN} = 3.465V$ or $2.625V$			10	μA
		$V_{CC} = V_{IN} = 3.465V$ or $2.625V$			150	μA
I_{IL}	Input Low Current	$V_{CC} = 3.465V$ or $2.625V$, $V_{IN} = 0V$	-150			μA
		$V_{CC} = 3.465V$ or $2.625V$, $V_{IN} = 0V$	-5			μA

Table 4D. LVPECL DC Characteristics, $V_{CC} = 3.3V \pm 5\%$, $V_{EE} = 0V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		$V_{CC} - 1.4$		$V_{CC} - 0.8$	V
V_{OL}	Output Low Voltage; NOTE 1		$V_{CC} - 2.0$		$V_{CC} - 1.6$	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50Ω to $V_{CC} - 2V$

Table 4E. LVPECL DC Characteristics, $V_{CC} = 2.5V \pm 5\%$, $V_{EE} = 0V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		$V_{CC} - 1.4$		$V_{CC} - 0.8$	V
V_{OL}	Output Low Voltage; NOTE 1		$V_{CC} - 2.0$		$V_{CC} - 1.5$	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.4		1.0	V

NOTE 1: Outputs terminated with 50Ω to $V_{CC} - 2V$

AC Electrical Characteristics

Table 5. AC Characteristics, $V_{CC} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $V_{EE} = 0V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{OUT}	Output Frequency		15.476		866.67	MHz
			975		1,300	MHz
f_I	Initial Accuracy	Measured at $25^{\circ}C$			± 10	ppm
f_S	Temperature Stability	Option code = A or B			± 100	ppm
		Option code = E or F			± 50	ppm
		Option code = K or L			± 20	ppm
f_A	Aging	Frequency drift over 10 year life			± 3	ppm
		Frequency drift over 15 year life			± 5	ppm
f_T	Total Stability	Option code A or B (10 year life)			± 113	ppm
		Option code E or F (10 year life)			± 63	ppm
		Option code K or L (10 year life)			± 33	ppm
jit(cc)	Cycle-to-Cycle Jitter; NOTE 1				30	ps
jit(per)	RMS Period Jitter, NOTE 1			1.9	2.8	ps
$\text{jit}(\emptyset)$	RMS Phase Jitter (Random); Fractional PLL feedback and $f_{XTAL}=100.000\text{MHz}$ (2xxx order codes)	$17\text{MHz} \leq f_{OUT} \leq 1300\text{MHz}$, NOTE 2, 3, 4		0.497	0.882	ps
	RMS Phase Jitter (Random); Integer PLL feedback and $f_{XTAL}=100.00\text{MHz}$ (1xxx order codes)	$500\text{MHz} \leq f_{OUT} \leq 1300\text{MHz}$, NOTE 2, 3, 4		0.232	0.322	ps
		$125\text{MHz} \leq f_{OUT} < 500\text{MHz}$, NOTE 2, 3, 4		0.250	0.384	ps
		$17\text{MHz} \leq f_{OUT} < 125\text{MHz}$, NOTE 2, 3, 4		0.275	0.405	ps
		$f_{OUT} = 156.25\text{MHz}$, NOTE 2, 3, 4		0.242	0.311	ps
		$f_{OUT} = 156.25\text{MHz}$, NOTE 2, 3, 5		0.275	0.359	ps
	RMS Phase Jitter (Random) Fractional PLL feedback and $f_{XTAL}=114.285\text{MHz}$ (0xxx order codes)	$17\text{MHz} \leq f_{OUT} \leq 1300\text{MHz}$, NOTE 2, 3, 4		0.474	0.986	ps
$\Phi_N(100)$	Single-side band phase noise, 100Hz from Carrier	$f_{OUT} = 156.25\text{MHz}$		-92		dBc/Hz
$\Phi_N(1k)$	Single-side band phase noise, 1kHz from Carrier	$f_{OUT} = 156.25\text{MHz}$		-120		dBc/Hz
$\Phi_N(10k)$	Single-side band phase noise, 10kHz from Carrier	$f_{OUT} = 156.25\text{MHz}$		-131		dBc/Hz
$\Phi_N(100k)$	Single-side band phase noise, 100kHz from Carrier	$f_{OUT} = 156.25\text{MHz}$		-138		dBc/Hz
$\Phi_N(1M)$	Single-side band phase noise, 1MHz from Carrier	$f_{OUT} = 156.25\text{MHz}$		-139		dBc/Hz
$\Phi_N(10M)$	Single-side band phase noise, 10MHz from Carrier	$f_{OUT} = 156.25\text{MHz}$		-154		dBc/Hz
t_R / t_F	Output Rise/Fall Time	20% to 80%	50		450	ps

AC Electrical Characteristics, continued

Table 5. AC Characteristics, $V_{CC} = 3.3V \pm 5\%$ or $2.5V \pm 5\%$, $V_{EE} = 0V$, $T_A = -40^{\circ}C$ to $85^{\circ}C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
odc	Output Duty Cycle		47		53	%
$t_{STARTUP}$	Oscillator Start-Up Time				20	ms
t_{SET}	Output Frequency Settling Time After FSEL Changed				1	ms

NOTE: Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE: XTAL parameters (initial accuracy, temperature stability, aging and total stability) are guaranteed by manufacturing.

NOTE 1: This parameter is defined in accordance with JEDEC standard 65.

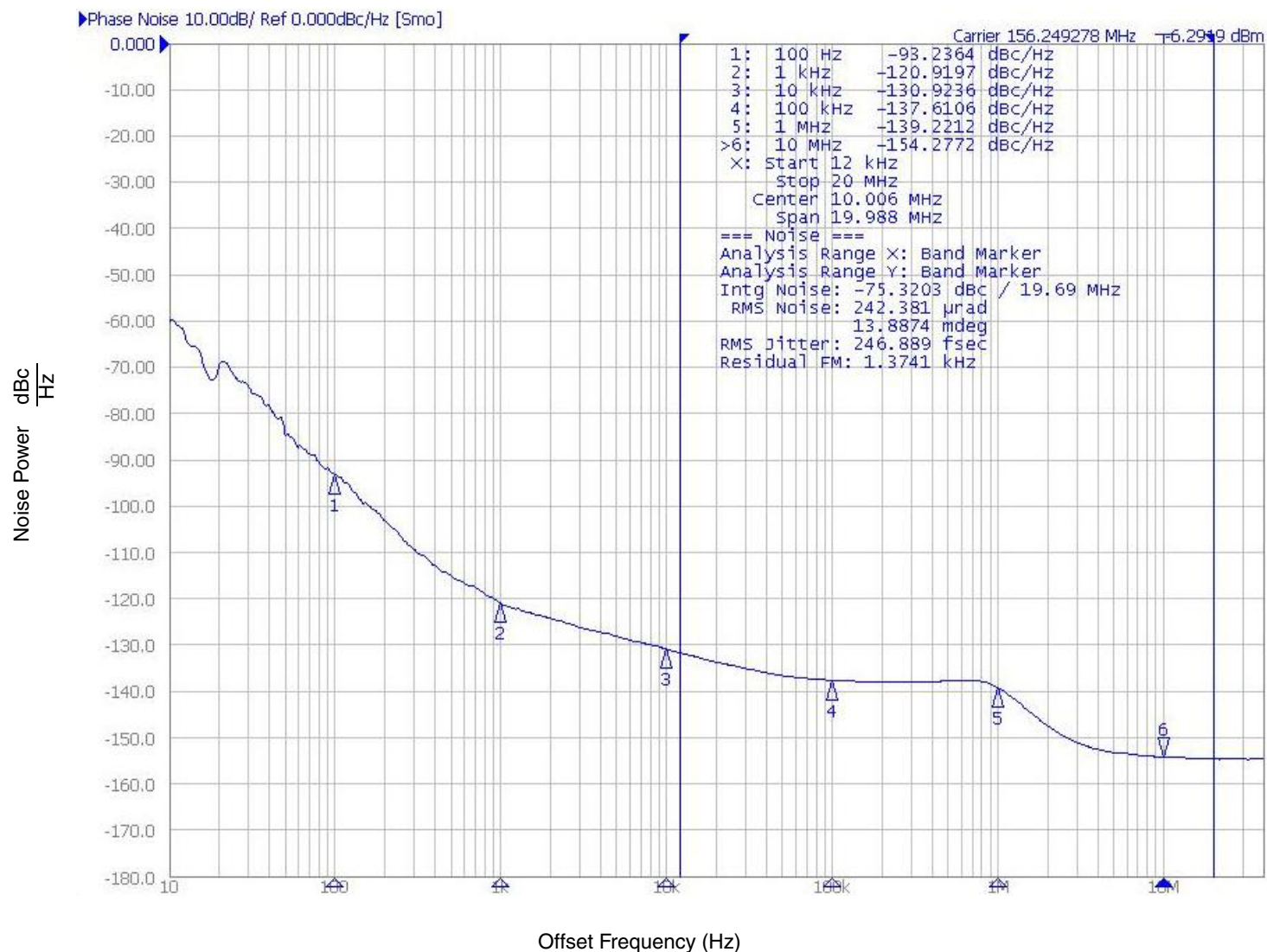
NOTE 2: Refer to the phase noise plots.

NOTE 3: Please see the FemtoClock NG Ceramic 5x7 Modules Programming guide for more information on PLL feedback modes and the optimum configuration for phase noise. Integer PLL feedback is the default operation for the dddd = 1xxx order codes.

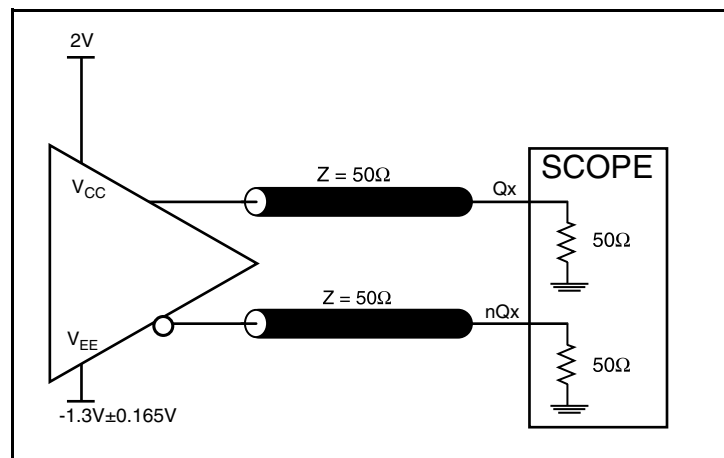
NOTE 4: Integration range: 12kHz - 20MHz.

NOTE 5: Integration range: 1kHz - 40MHz.

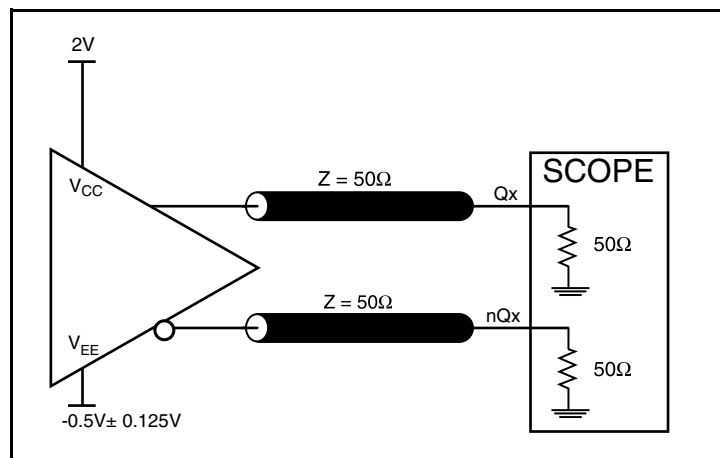
Typical Phase Noise at 156.25MHz (12kHz - 20MHz)



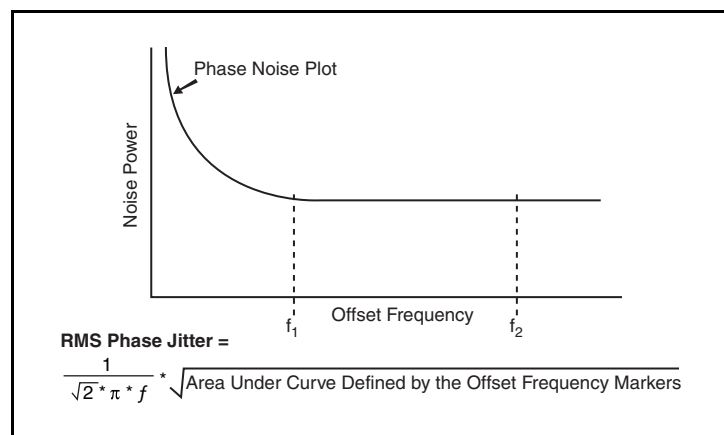
Parameter Measurement Information



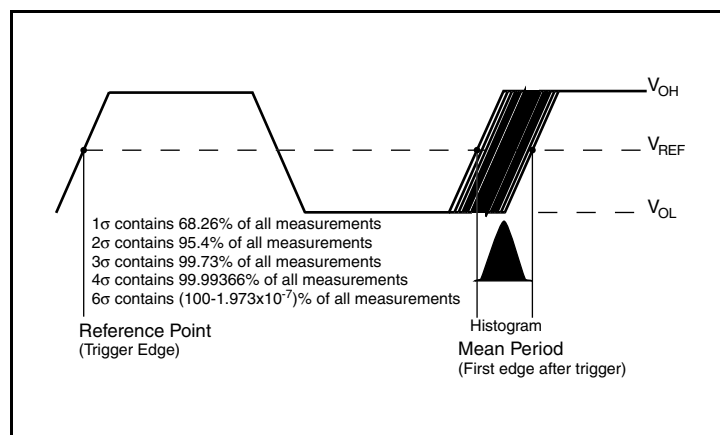
3.3V Output Load Test Circuit



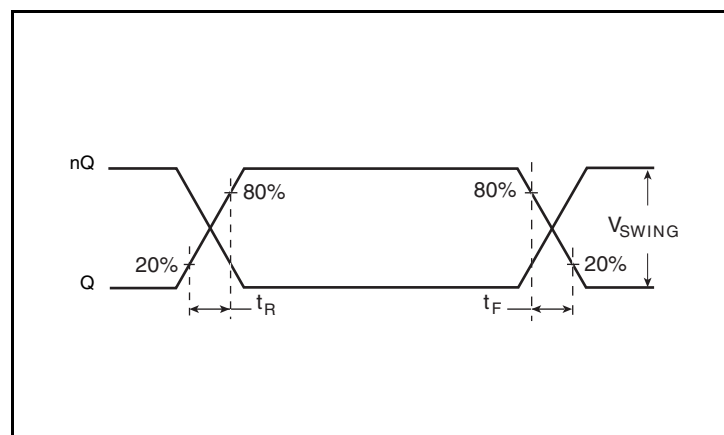
2.5V Output Load Test Circuit



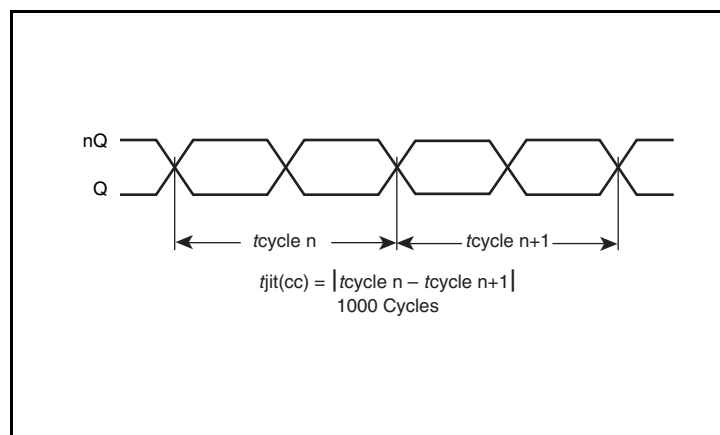
RMS Phase Jitter



RMS Period Jitter

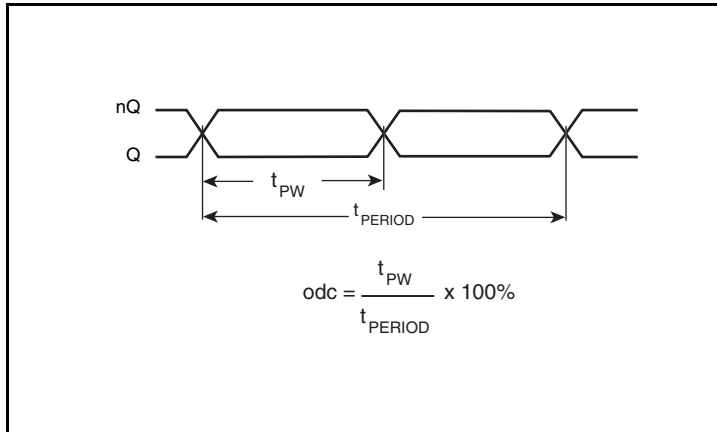


Output Rise/Fall Time



Cycle-to-Cycle Jitter

Parameter Measurement Information, continued



Output Duty Cycle/Pulse Width/Period

Applications Information

Recommendations for Unused Input Pins

Inputs:

LVCMOS Control Pins

All control pins have internal pullups or pulldowns; additional resistance is not required but can be added for additional protection. A 1kΩ resistor can be used.

Termination for 3.3V LVPECL Outputs

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

The differential outputs are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50Ω

transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 1A and 1B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

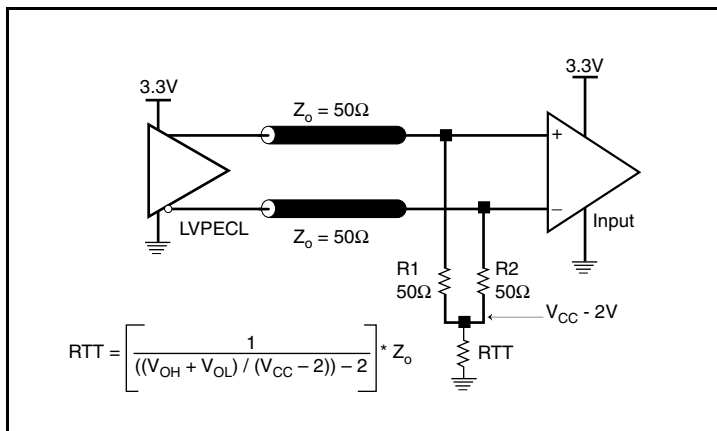


Figure 1A. 3.3V LVPECL Output Termination

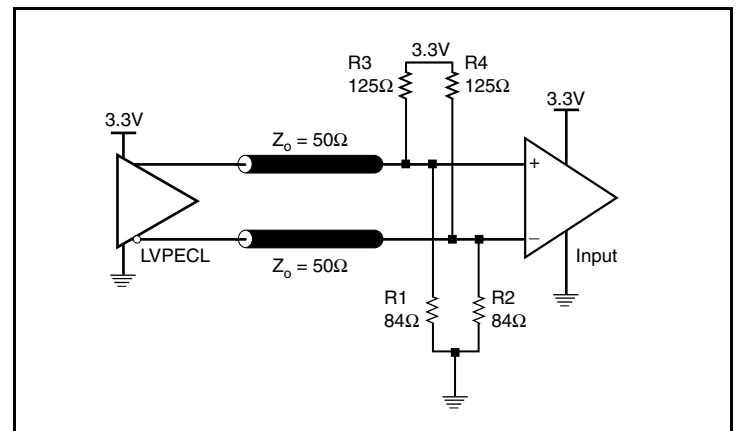


Figure 1B. 3.3V LVPECL Output Termination

Termination for 2.5V LVPECL Outputs

Figure 2A and Figure 2B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating 50Ω to $V_{CC} - 2V$. For $V_{CC} = 2.5V$, the $V_{CC} - 2V$ is very close to ground

level. The $R3$ in Figure 2B can be eliminated and the termination is shown in Figure 2C.

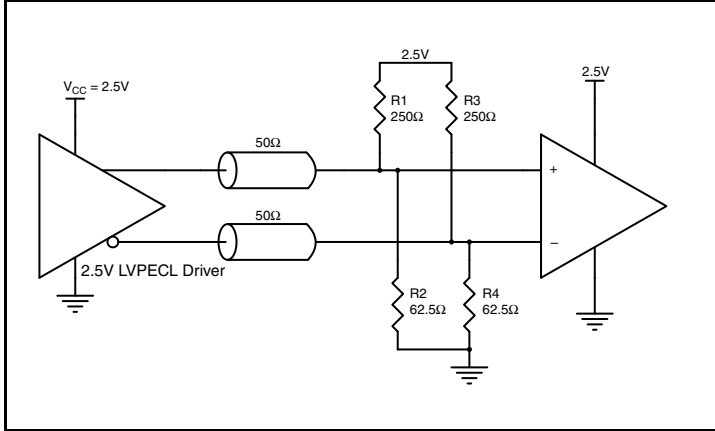


Figure 2A. 2.5V LVPECL Driver Termination Example

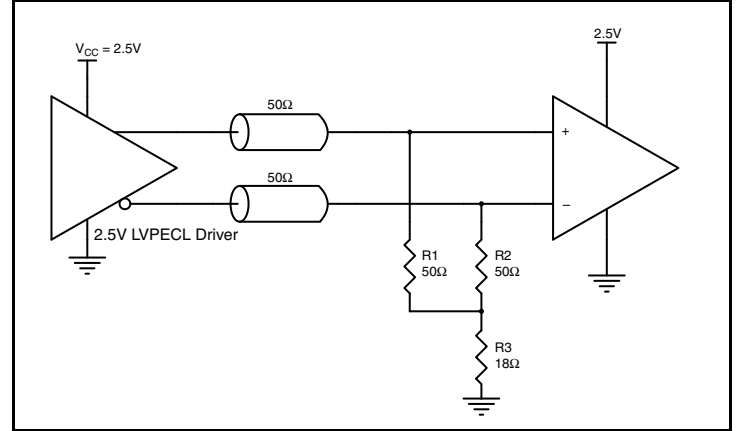


Figure 2B. 2.5V LVPECL Driver Termination Example

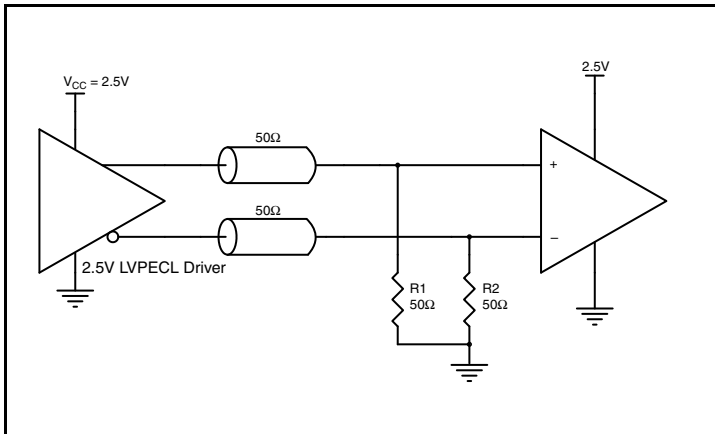


Figure 2C. 2.5V LVPECL Driver Termination Example

Schematic Layout

Figure 3 shows an example IDT8N3D085 application schematic. The schematic example focuses on functional connections and is intended as an example only and may not represent the exact user configuration. Refer to the pin description and functional tables in the datasheet to ensure the logic control inputs are properly set. For example OE and FSEL can be configured from an FPGA instead of set with pull up and pull down resistors as shown.

As with any high speed analog circuitry, the power supply pins are vulnerable to random noise, so to achieve optimum jitter performance isolation of the V_{CC} pin from power supply is required. In order to achieve the best possible filtering, it is recommended that the placement of the filter components be on the device side of the

PCB as close to the power pins as possible. If space is limited, the 0.1 μ F capacitor on the V_{CC} pin must be placed on the device side with direct return to the ground plane through vias. The remaining filter components can be on the opposite side of the PCB.

Power supply filter component recommendations are a general guideline to be used for reducing external noise from coupling into the devices. The filter performance is designed for a wide range of noise frequencies. This low-pass filter starts to attenuate noise at approximately 10kHz. If a specific frequency noise component is known, such as switching power supplies frequencies, it is recommended that component values be adjusted and if required, additional filtering be added. Additionally, good general design practices for power plane voltage stability suggests adding bulk capacitance in the local area of all devices.

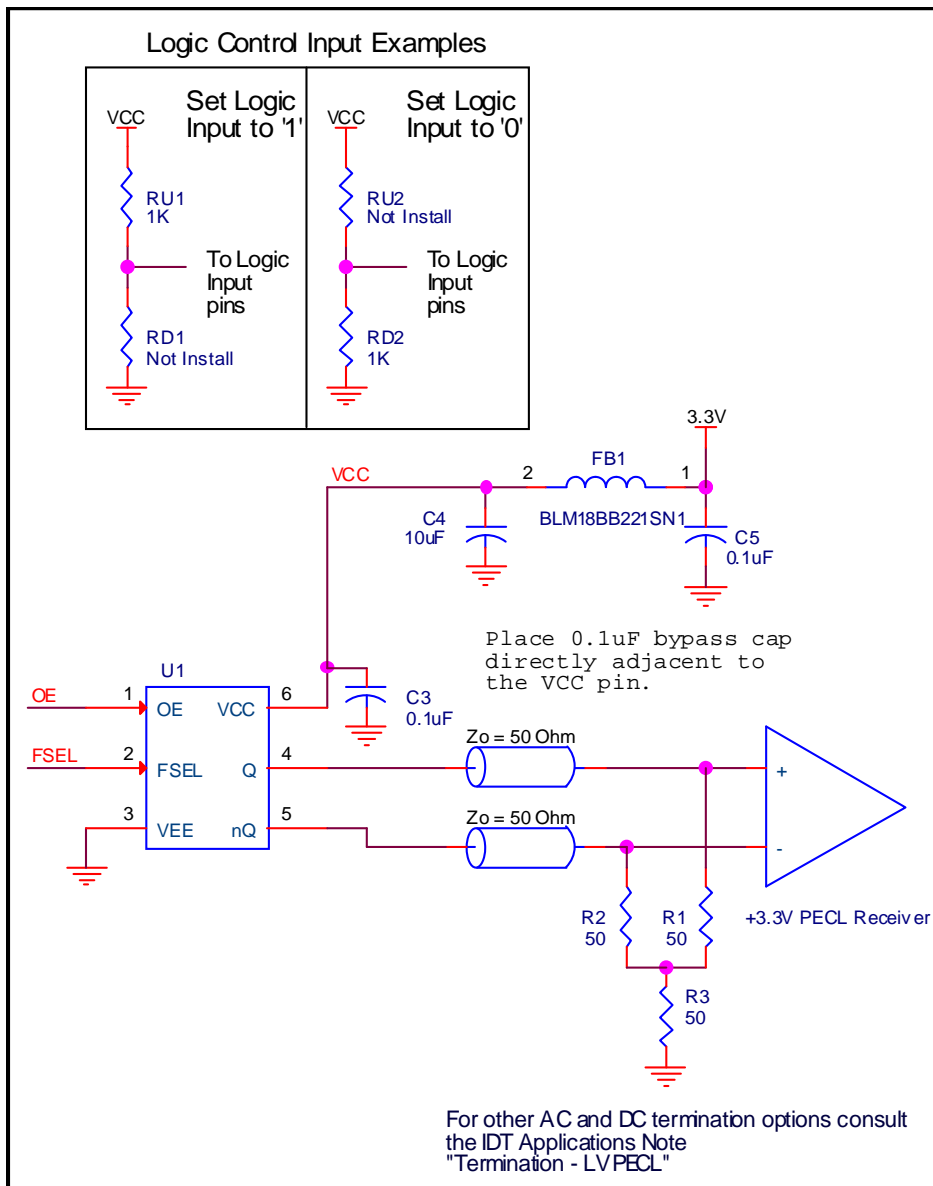


Figure 3. IDT8N3D085 Application Schematic

Power Considerations

This section provides information on power dissipation and junction temperature for the IDT8N3D085. Equations and example calculations are also provided.

1. Power Dissipation

The total power dissipation for the IDT8N3D085 is the sum of the core power plus the output power dissipated due to the loading. The following is the power dissipation for $V_{CC} = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating output power dissipated due to the loading.

- Power (core)_{MAX} = $V_{CC_MAX} * I_{EE_MAX} = 3.465V * 148mA = 512.82mW$
- Power (outputs)_{MAX} = **32mW/Loaded Output pair**

Total Power_{MAX} (3.465V, with all outputs switching) = $512.82mW + 32mW = 544.82mW$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad directly affects the reliability of the device. The maximum recommended junction temperature is 125°C. Limiting the internal transistor junction temperature, T_j , to 125°C ensures that the bond wire and bond pad temperature remains below 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming no air flow and a multi-layer board, the appropriate value is 49.4°C/W per Table 6 below.

Therefore, T_j for an ambient temperature of 85°C with all outputs switching is:

$$85^{\circ}C + 0.545W * 49.4^{\circ}C/W = 111.9^{\circ}C. \text{ This is below the limit of } 125^{\circ}C.$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (multi-layer).

Table 6. Thermal Resistance θ_{JA} for 6 Lead Ceramic 5mm x 7mm Package, Forced Convection

θ_{JA} by Velocity			
Meters per Second	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	49.4°C/W	44.2°C/W	42.1°C/W

3. Calculations and Equations.

The purpose of this section is to calculate the power dissipation for the LVPECL output pair.

LVPECL output driver circuit and termination are shown in *Figure 4*.

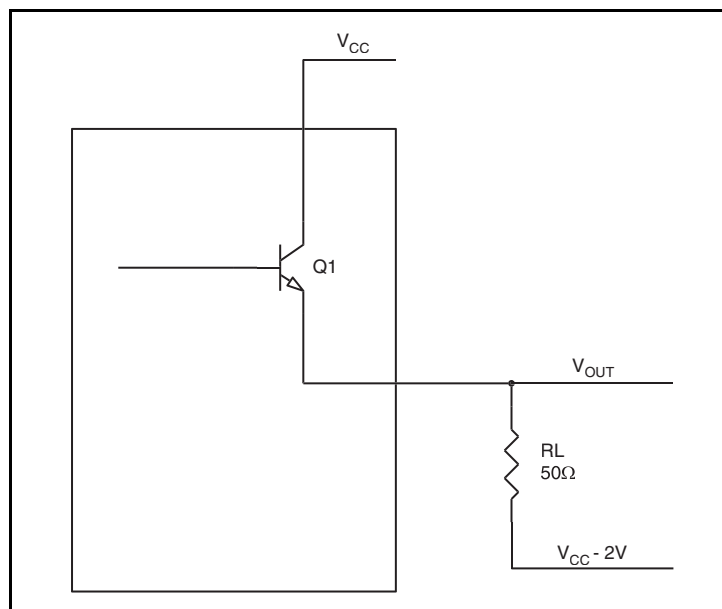


Figure 4. LVPECL Driver Circuit and Termination

To calculate output power dissipation due to the loading, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CC} - 2V$.

- For logic high, $V_{OUT} = V_{OH_MAX} = V_{CC_MAX} - 0.8V$
($V_{CC_MAX} - V_{OH_MAX}$) = **0.8V**
- For logic low, $V_{OUT} = V_{OL_MAX} = V_{CC_MAX} - 1.6V$
($V_{CC_MAX} - V_{OL_MAX}$) = **1.6V**

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - (V_{CC_MAX} - V_{OH_MAX}))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - 0.8V)/50\Omega] * 0.8V = \mathbf{19.2mW}$$

$$Pd_L = [(V_{OL_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - (V_{CC_MAX} - V_{OL_MAX}))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - 1.6V)/50\Omega] * 1.6V = \mathbf{12.8mW}$$

$$\text{Total Power Dissipation per output pair} = Pd_H + Pd_L = \mathbf{32mW}$$

Reliability Information

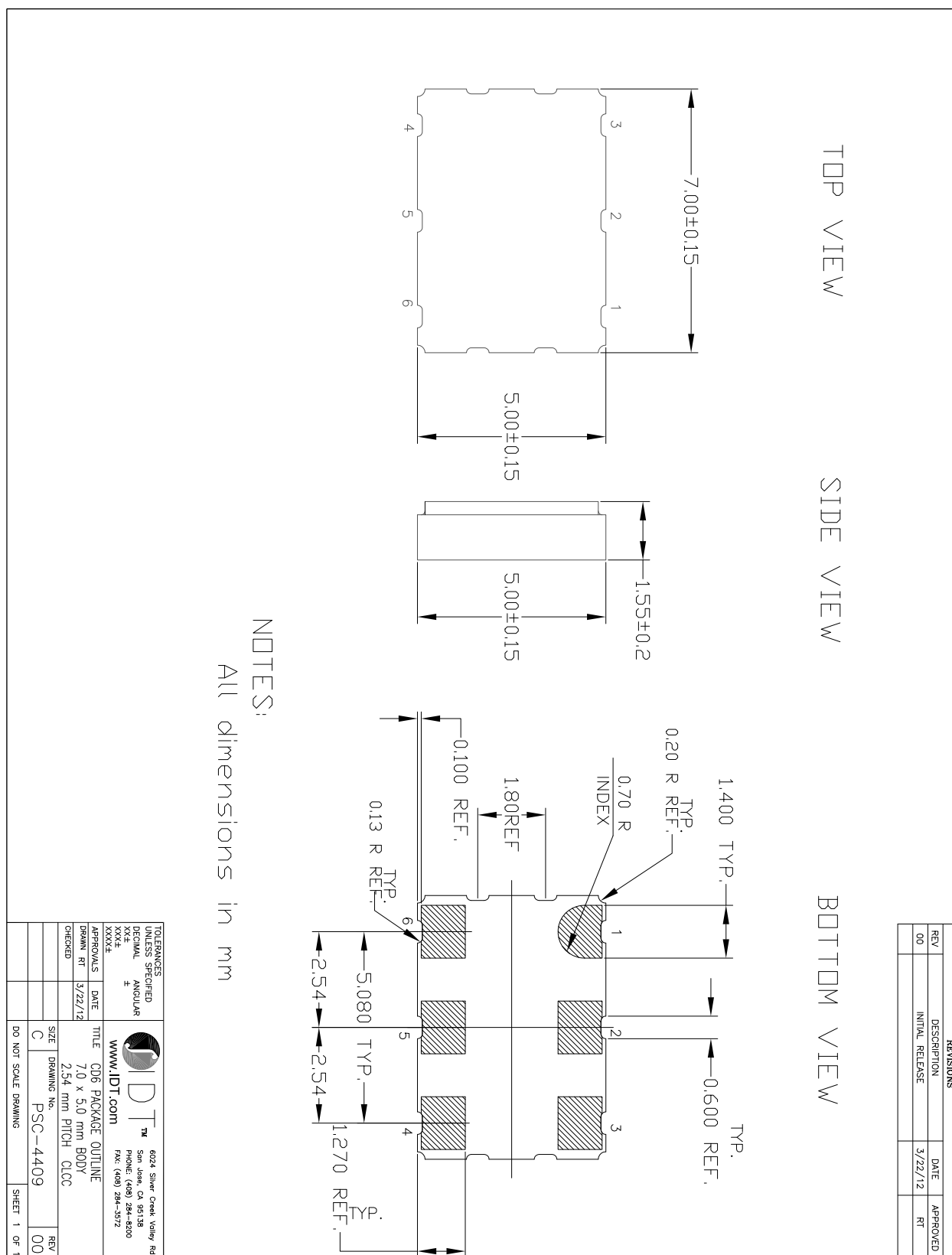
Table 7. θ_{JA} vs. Air Flow Table for a 6-lead Ceramic 5mm x 7mm Package

θ_{JA} vs. Air Flow			
Meters per Second	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	49.4°C/W	44.2°C/W	42.1°C/W

Transistor Count

The transistor count for IDT8N3D085 is: 47,511

Package Outline and Package Dimensions

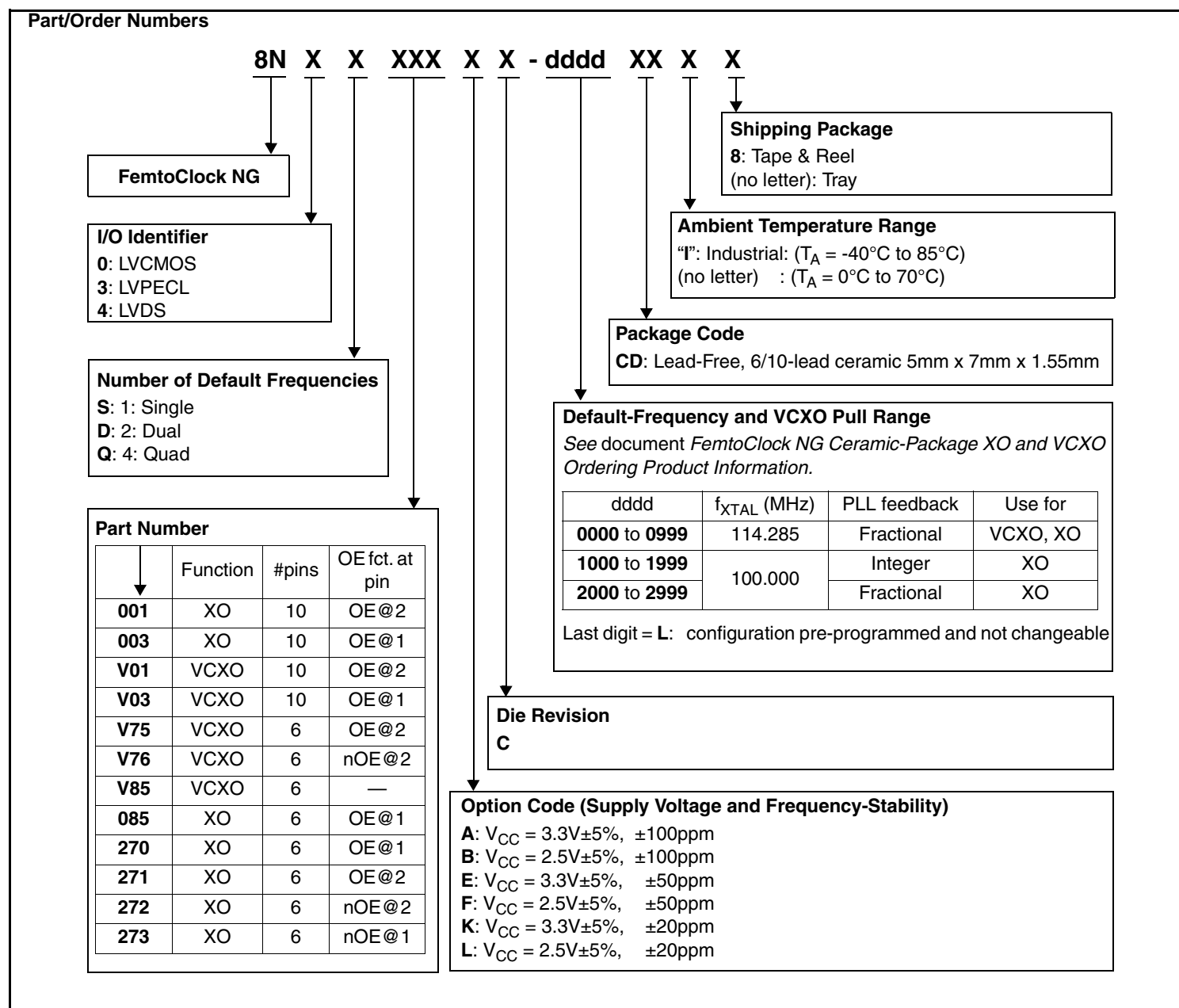


Ordering Information for FemtoClock NG Ceramic-Package XO and VCXO Products

The programmable VCXO and XO devices support a variety of device options such as the output type, number of default frequencies, internal crystal frequency, power supply voltage, ambient temperature range and the frequency accuracy. The device options, default frequencies and default VCXO pull range must be specified at the time of order and are programmed by IDT before the shipment. The table below specifies the available order codes, including the device options and default frequency configurations. Example part number: the order code 8N3QV01FG-0001CDI specifies a programmable, quad default-frequency VCXO with a voltage supply of 2.5V, a LVPECL output, a ± 50 ppm crystal frequency accuracy,

contains a 114.285MHz internal crystal as frequency source, industrial temperature range, a lead-free (6/6 RoHS) 6-lead ceramic 5mm x 7mm x 1.55mm package and is factory-programmed to the default frequencies of 100, 122.88, 125 and 156.25MHz and to the VCXO pull range of min. ± 100 ppm.

Other default frequencies and order codes are available from IDT on request. For more information on available default frequencies, see the *FemtoClock NG Ceramic-Package XO and VCXO Ordering Product Information* document.



NOTE: For order information, also see the *FemtoClock NG Ceramic-Package XO and VCXO Ordering Product Information* document.

Device Marking

Table 8. Device Marking

Marking	Industrial Temperature Range (T _A = -40°C to 85°C)	Commercial Temperature Range (T _A = 0°C to 70°C)
	N3D085yCddddI	8N3D085yCdddd
	y = Option Code, dddd=Default-Frequency and VCXO Pull Range	

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